Tepla M4L O₂ Plasma Asher

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Process Summary
Open-load plasma asher used for removing organic materials, surface plasma cleaning, or surface modification/roughening of select materials using O₂, Ar, and CF₄. Process conditions are generally from 0-2000 mTorr with an RF power of 0-500W.

Process Preparation
Users should ensure their sample is placed on the desired stage (biased or grounded).

Only these Materials are Allowed
- Silicon
- SiO₂
- SiNx
- Photoresist

Restricted Materials (Staff permission req’d for each use)
- Metals (case-by-case)

KnownForbidden Materials
- Metallic In, Pb, Ga, Zn, Sn, Se, Te (even unexposed)
- Alkali & Alkali Earth Metals (even unexposed)

For any material not listed or if uncertain, **ASK** the Tool Owner!